

# Incremental Gate Sizing for Late Process Changes

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# Outline

1. Process change
2. ECO Costs
3. ECO Aware Design via LPECO
4. Experiments
5. Summary

# Manufacturing process

- The foundry provides designers with a model of the **manufacturing process**
  - Information about the way transistors and interconnect
  - BSIM / PTM models, Liberty (.lib) model
- Model contains information about:
  - **Electrical parameters:** threshold voltage, saturation current, leakage current, I-V characteristics, interconnect resistance, capacitance, dielectric information
  - **Geometrical parameters:** gate length, gate width, source / gate / drain capacitance

# Manufacturing Process Changes

- Aggressive schedules = uncertainty
  - From ITRS 2008:

*Table DESN9 Design for Manufacturability Technology Requirements*

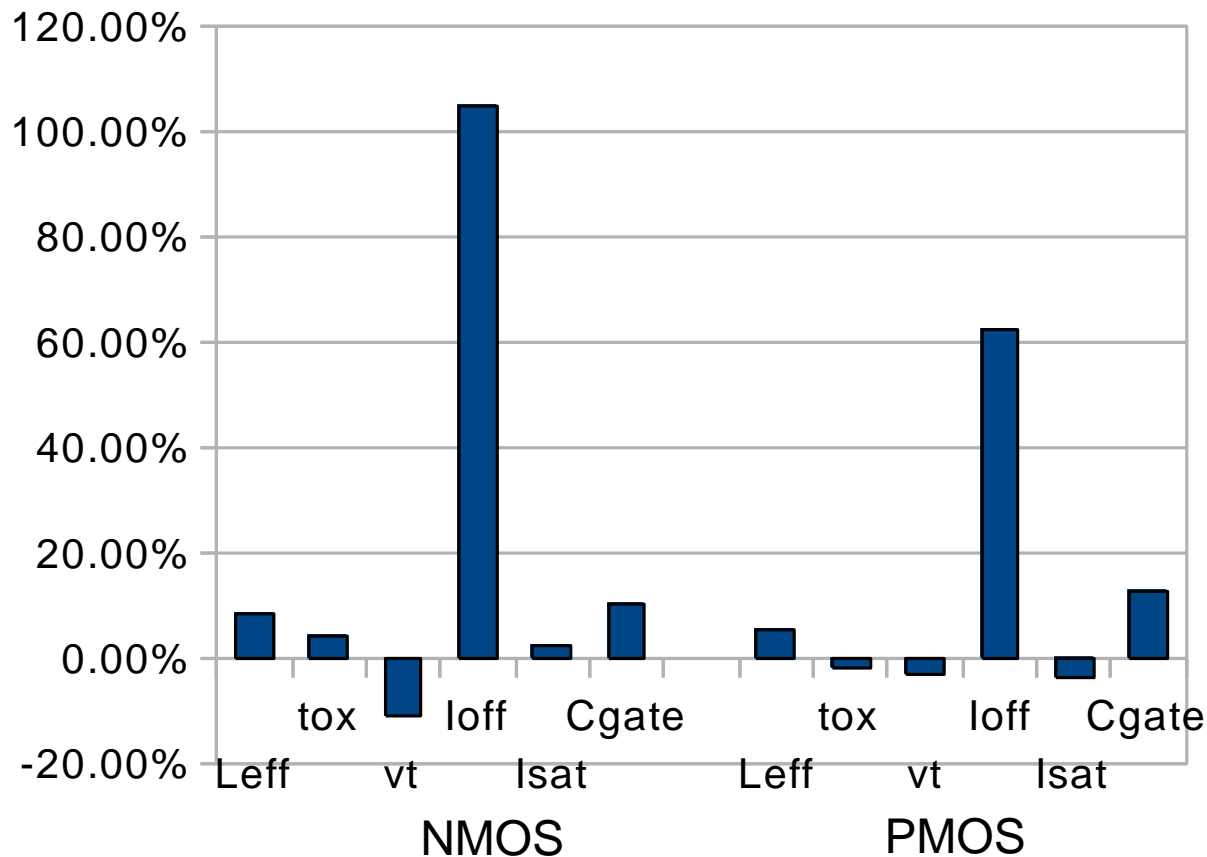
<i>Year of Production</i>	<i>2007</i>	<i>2008</i>	<i>2009</i>	<i>2010</i>	<i>2011</i>	<i>2012</i>
Normalized mask cost from public and IDM data	1	1.3	1.7	2.3	3	3.9
% $V_{dd}$ variability: % variability seen in on-chip circuits	10%	10%	10%	10%	10%	10%
% $V_{th}$ variability: doping variability impact on $V_{th}$ , (minimum size devices, memory)	31%	35%	40%	40%	40%	58%
% $V_{th}$ variability: includes all sources	33%	37%	42%	42%	42%	58%
% $V_{th}$ variability: typical size logic devices, all sources	16%	18%	20%	20%	20%	26%
% CD variability	12%	12%	12%	12%	12%	12%
% circuit performance variability circuit comprising gates and wires	46%	48%	49%	51%	60%	63%
% circuit total power variability circuit comprising gates and wires	56%	57%	63%	68%	72%	76%
% circuit leakage power variability circuit comprising gates and wires	124%	143%	186%	229%	255%	281%

**Solutions known, under development**

**Solutions not known**

# 45nm Manufacturing Process change Example

- From April 2008 to March 2010
  - Real data from a commercial 45nm process



# Engineering Change Order (ECO)

- Design changes that are made late in the design process are referred to as an **Engineering Change Order (ECO)**

## Example:

HotFab Foundry provides Design Tech Inc. with an updated set of manufacturing parameters that decrease  $I_{\text{sat}}$  (the saturation current), causing their current designs to violate timing.

They fix their design using an ECO which includes changing the gate sizes (e.g. INV X1 -> INV X8), and routing changes

**ECO = design / tool time + delays! (€€€ / \$\$\$ !)**

**ECOs should minimize implementation costs!**

# What does an ECO cost?

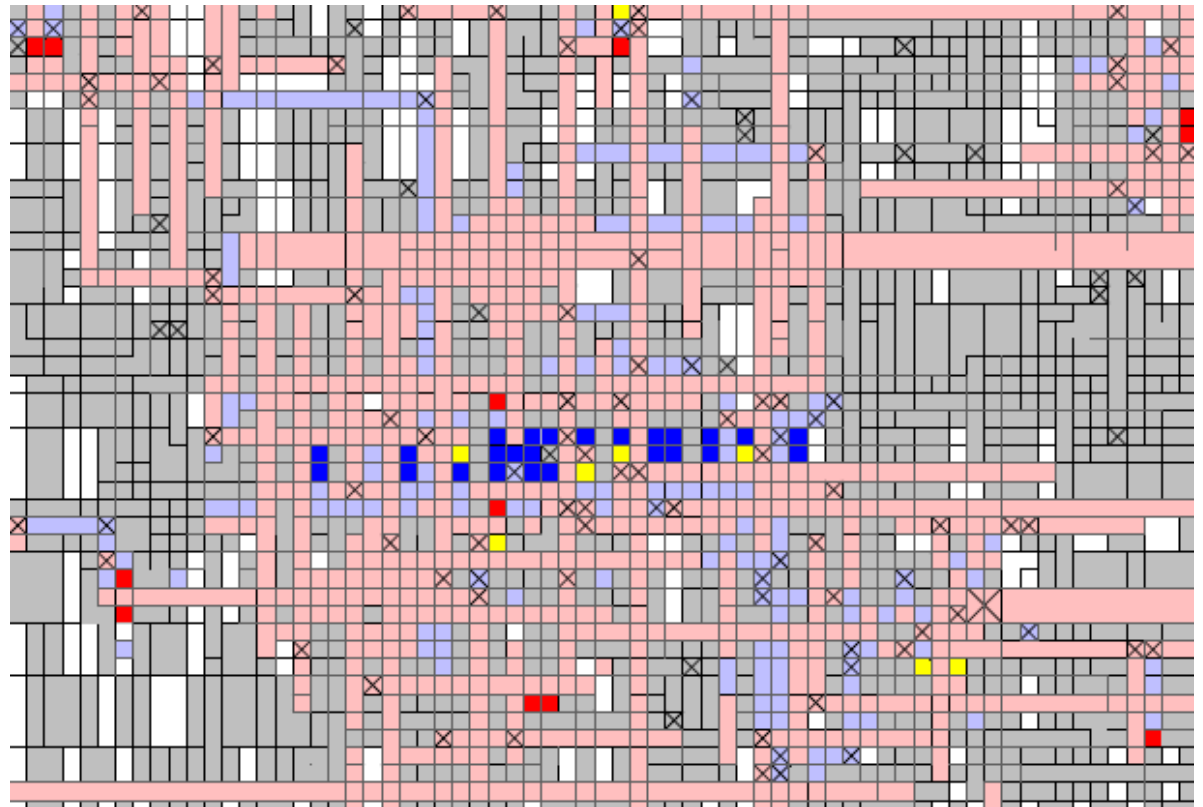
## Legend

Added nets

Deleted nets

Moved cells

Resized cells



**Quantify ECO cost → Guide Optimization**

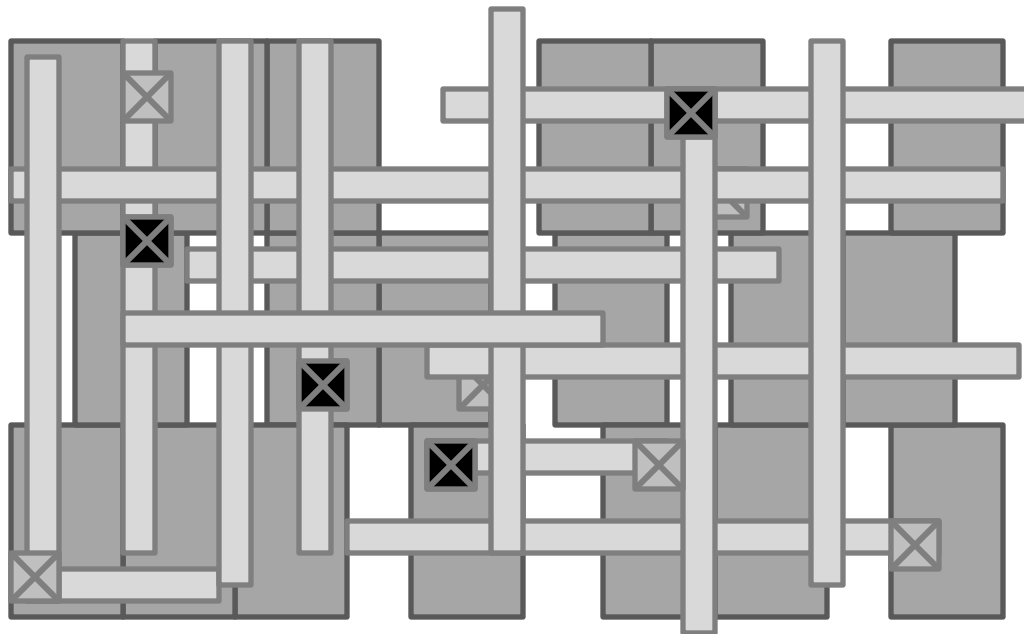
# Proposed Measures for ECO Cost

- ECO Area Cost: Changed area
  - Amount of area that must be reanalyzed for
    - Parasitic Extraction & LVS / DRC
  - Potential layout errors to be corrected
- ECO Timing Cost: Changed timing
  - The effect of the ECO on the timing signal (circuit topology):
    - # of pins with unnecessary timing changes
      - The pin was not violating timing before the ECO
  - Changes cause slew, crosstalk violations, in paths that run through the ECO
  - Potential timing errors to be corrected



# ECO Area Cost

- Measured as the amount of area, in  $\mu\text{m}^2$  that has changed
  - Includes gate area, metal wires and vias



# Estimating ECO Area Cost

- Performing trial ECOs are too costly:
  - Impractical to try all possible ECO moves
  - Estimates of routing cost are needed to guide optimization
- Area Cost Estimated as a linear function of:
  - Number of changed pins
  - Number dislocated pins
    - Old and new locations do not overlap
  - Area of the pin bounding box
  - Congestion over the pin bounding box



# Estimating ECO Area Cost

- Area Cost Estimate:

$m_1$ : Number of affected pins

$m_2$ : Number of dislocated pins (*old locations and new locations do not overlap*)

$m_3$ : Pin bounding box area

$m_4$ : Utilized area over pin bounding box (*routing over all layers*)

$$\hat{C}_{\text{area}} = \sum_{i=1}^4 a_i m_i + b$$

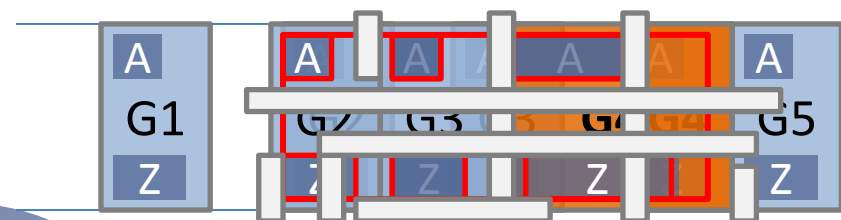
$$a_1 = 0.0367 \mu\text{m}^2/\text{pin}$$

$$a_2 = 0.186 \mu\text{m}^2/\text{pin}$$

$$a_3 = 5.35$$

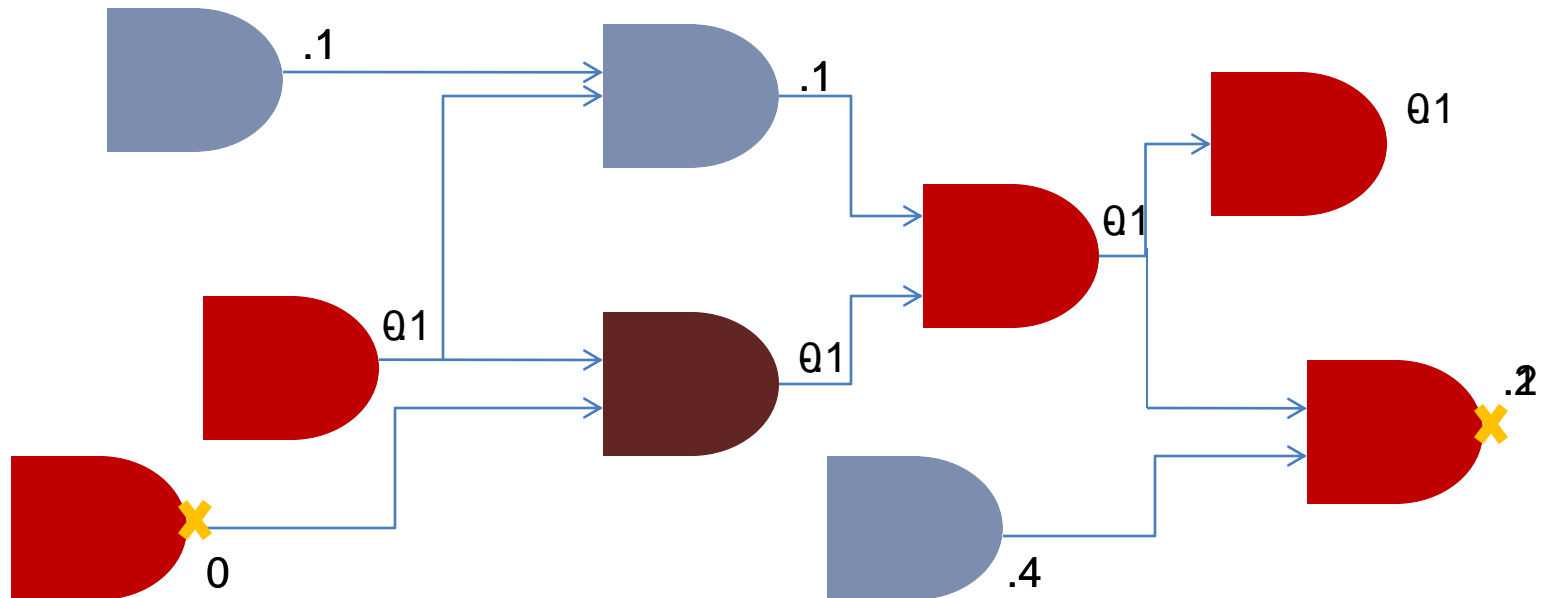
$$a_4 = 9.65$$

$$b = .264 \mu\text{m}^2$$



# ECO Timing Cost

- Timing is affected downstream and upstream
- ECO Timing cost is defined as:
  - # of non-critical pins that are upstream and downstream from an ECO



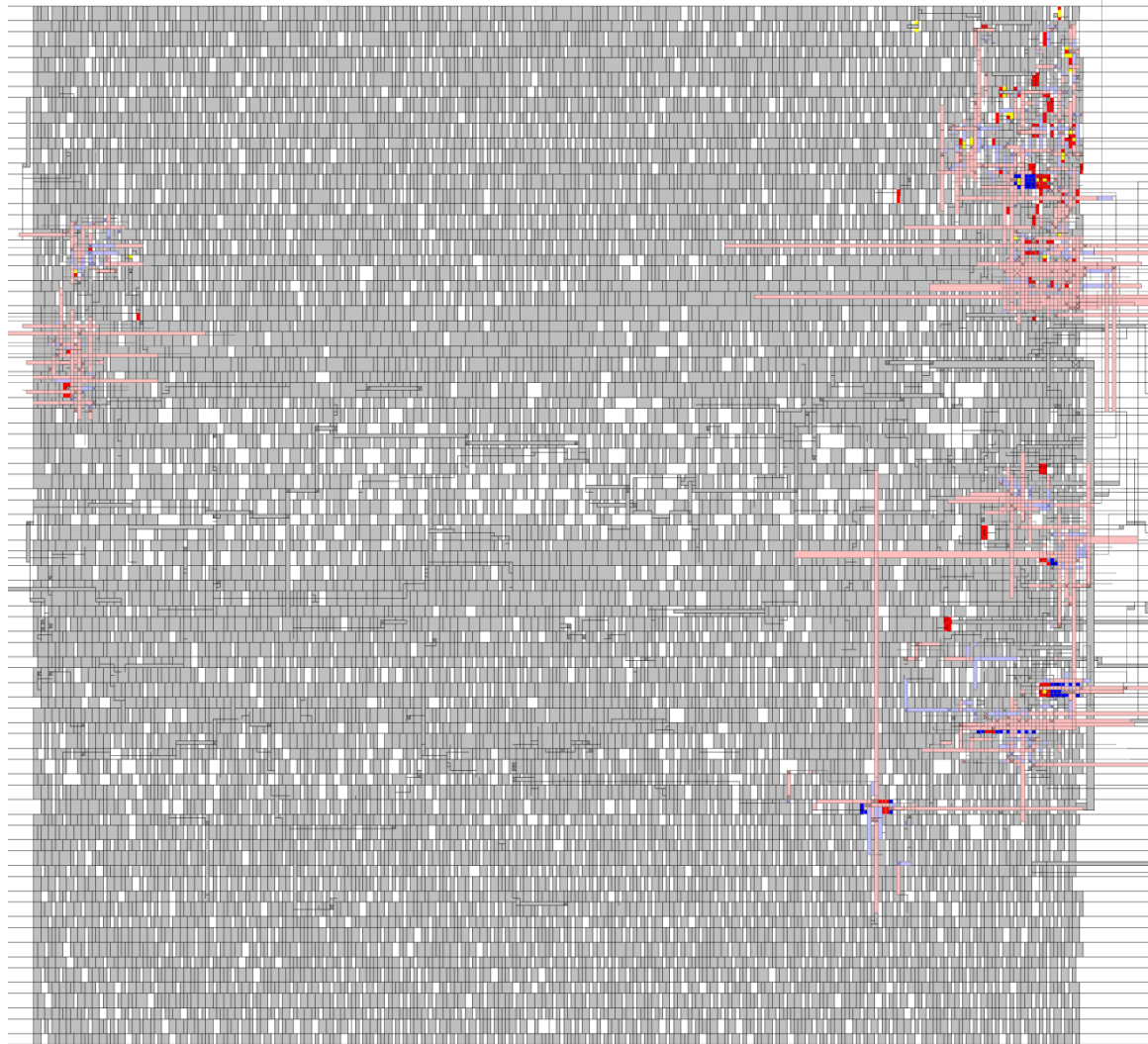
# ECO Cost Example:

Timing cost:

118.9  $\mu\text{m}^2$

Pin Cost:

2838 pins



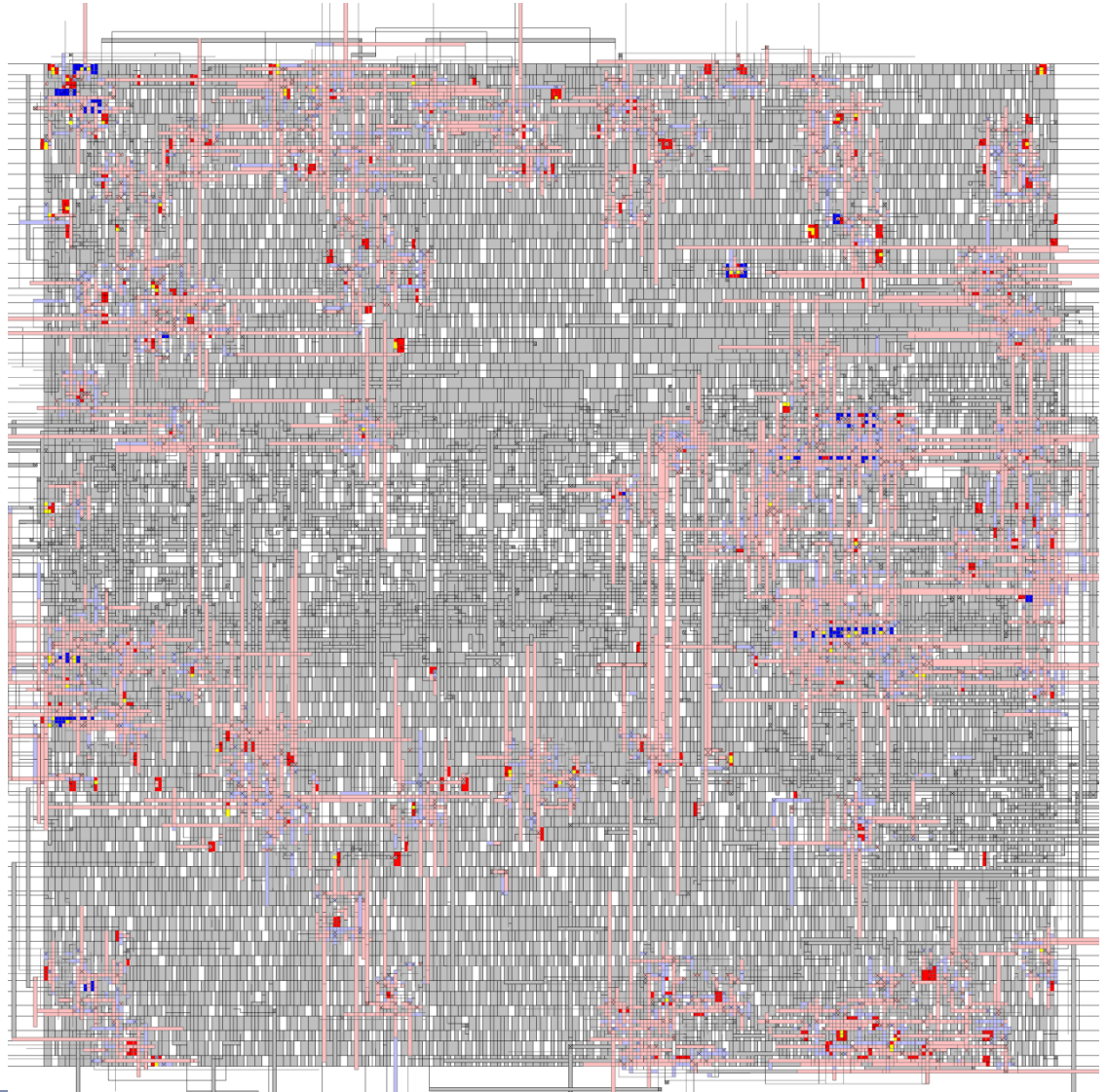
# ECO Cost Example:

Timing cost:

586.6  $\mu\text{m}^2$

Pin Cost:

10198 pins



# ECO-cost aware design via LPECO

- Linear programming based ECO gate sizing
  - Objective: ECO cost + Power cost
  - Constraints: Delay (timing closure)
  - Timing, power and ECO are modeled as a function of the candidate gate size

Example: Gate 1

		Gate Size Candidates		
Current size		X1	X4	X8
X2	Timing cost:	1	1	1
	Area cost:	2	4	6
	Power cost:	1	4	8
	Delay:	4	3	2

# ECO-cost aware design via LPECO

$$\text{minimize } \sum_{i,k} p_{ik} y_{ik} + \gamma_t \hat{c}_{\text{timing}}(\mathbf{y}; \mathbf{x}) + \gamma_a \hat{c}_{\text{area}}(\mathbf{y}; \mathbf{x})$$

$$\text{subject to } t_i + d_{i0} + \sum_k \delta_{ik} y_{ik} \leq t_j, \quad \forall i \in \text{fo}(j)$$

$$t_i \leq T_{\max}$$

$$\sum_k y_{ik} \leq 1, \quad \forall i$$

$$0 \leq y_{ik} \leq 1$$

$t$  : arrival time for gate  $i$

$d_{i0}$  : current delay for gate  $i$

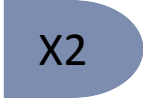
$\delta_{ik}$  : change in delay of gate  $i$  under size  $k$

$y_{ik}$  : assignment variable of gate  $i$  to size  $k$

$p_{ik}$  : change in leakage power of gate  $i$  to size  $k$

( $\delta_{ik}, d_{i0}$  are from the commercial tool)

## Example: Gate 1

Current size		Gate Size Candidates			
		X1	X4	X8	
		( $y_{11} = 1$ )	( $y_{14} = 1$ )	( $y_{18} = 1$ )	
	Timing cost:	1	1	1	
	Area cost:	2	4	6	
	Power cost:	-1 ( $p_{11}$ )	3 ( $p_{14}$ )	7 ( $p_{18}$ )	
	Delay change:	4 ( $\delta_{11}$ )	3 ( $\delta_{14}$ )	2 ( $\delta_{18}$ )	



# Experimental Setup

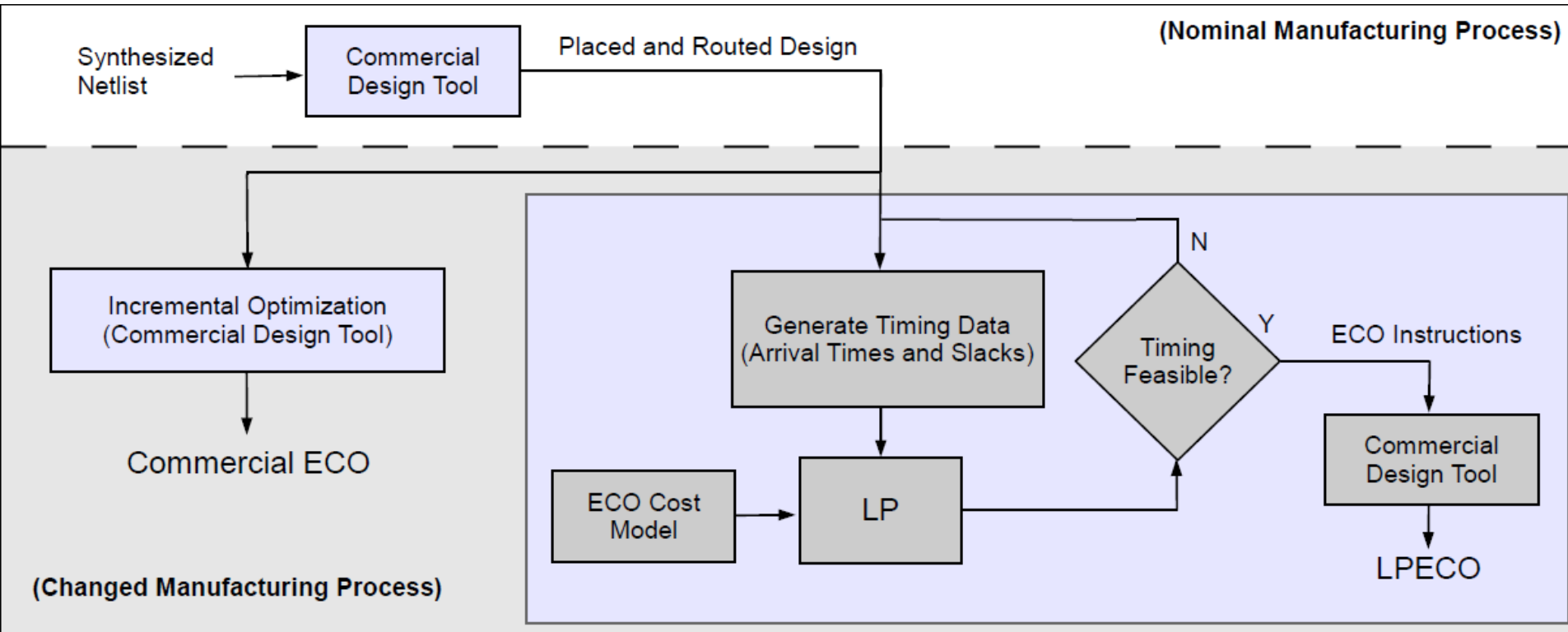
- 45nm Nangate Open Cell Library
- Manufacturing process change:

	Nmos	Pmos
$V_{th}$	-10%	-5%
$t_{ox}$	+5%	-5%
$C_{gate}$	+10%	+10%
$l_{eff}$	+5%	+5%

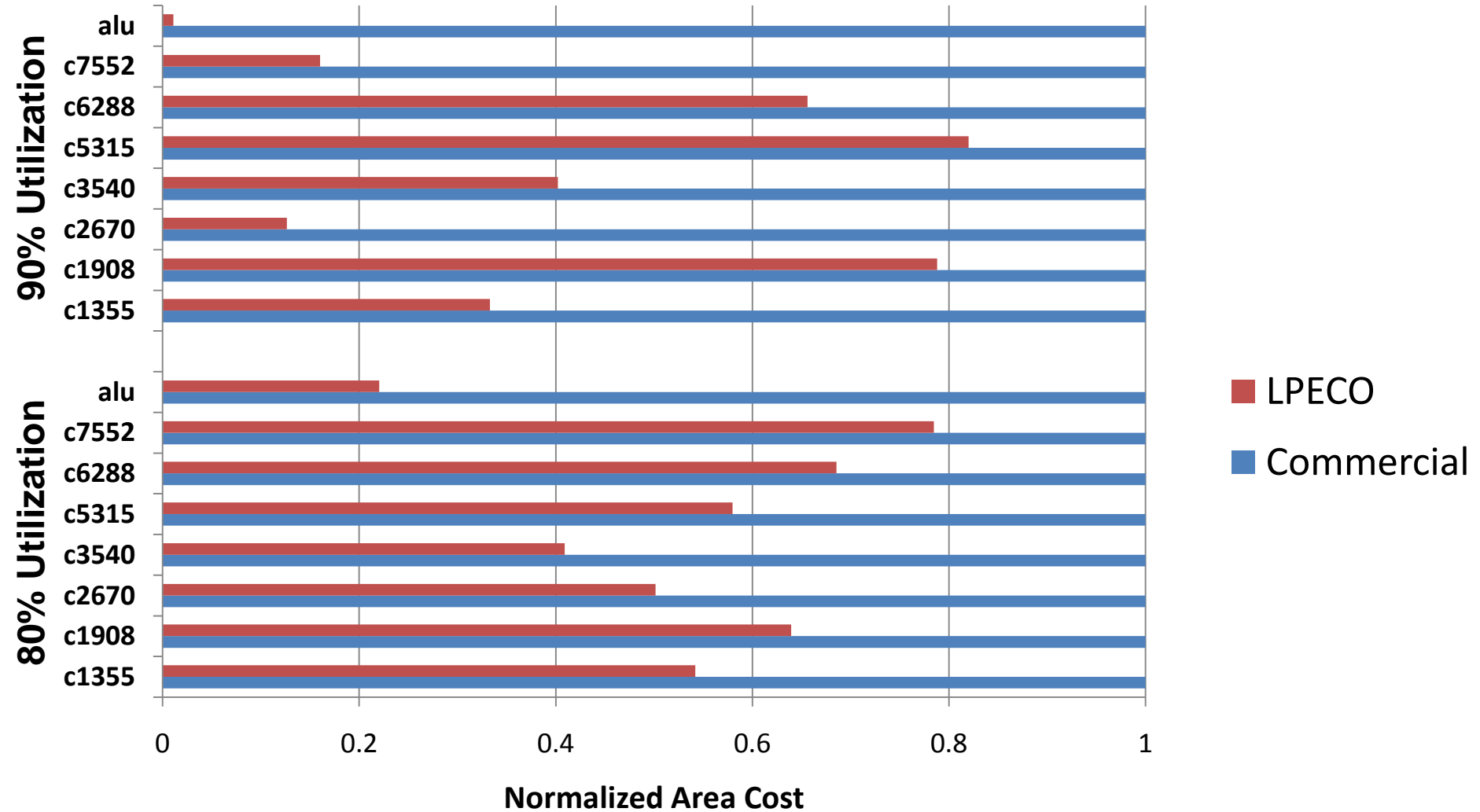
- ECO's are performed by a leading commercial design tool
- Runtime of LPECO ~.01 to 103s

# Experimental Setup

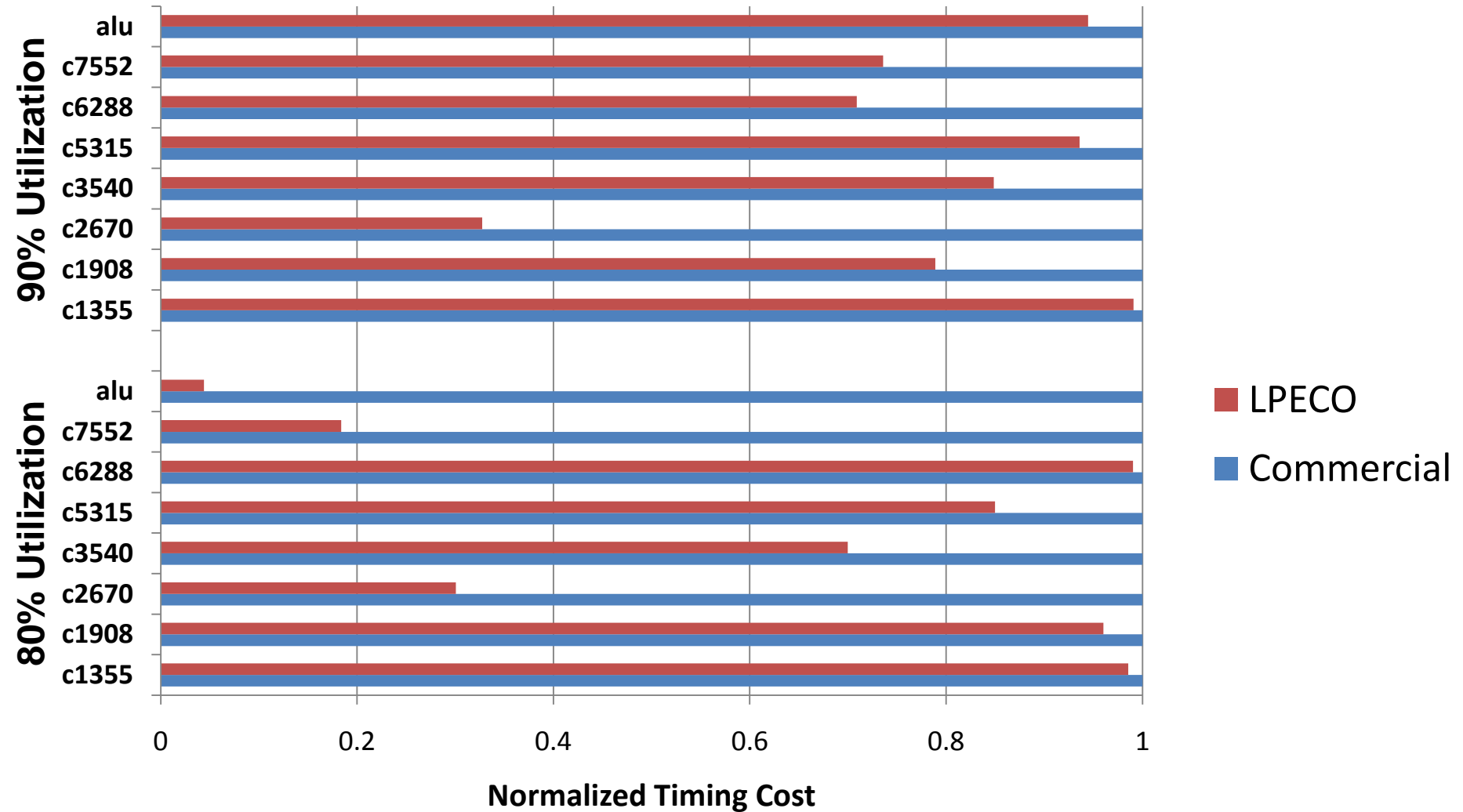
	Nmos	Pmos
$V_{th}$	-10%	-5%
$t_{ox}$	+5%	-5%
$C_{gate}$	+10%	+10%
$l_{eff}$	+5%	+5%



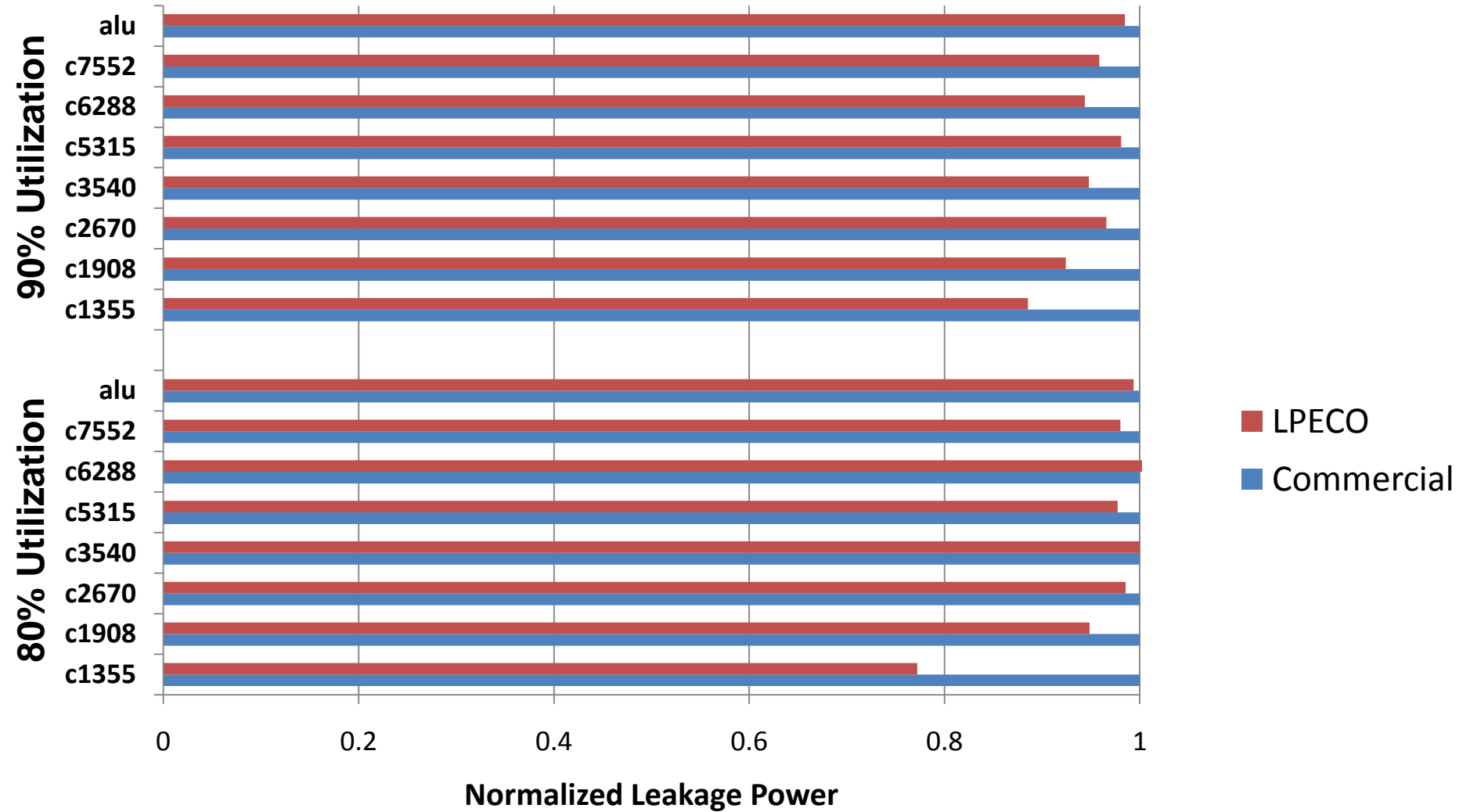
# Results: Area Cost Comparison



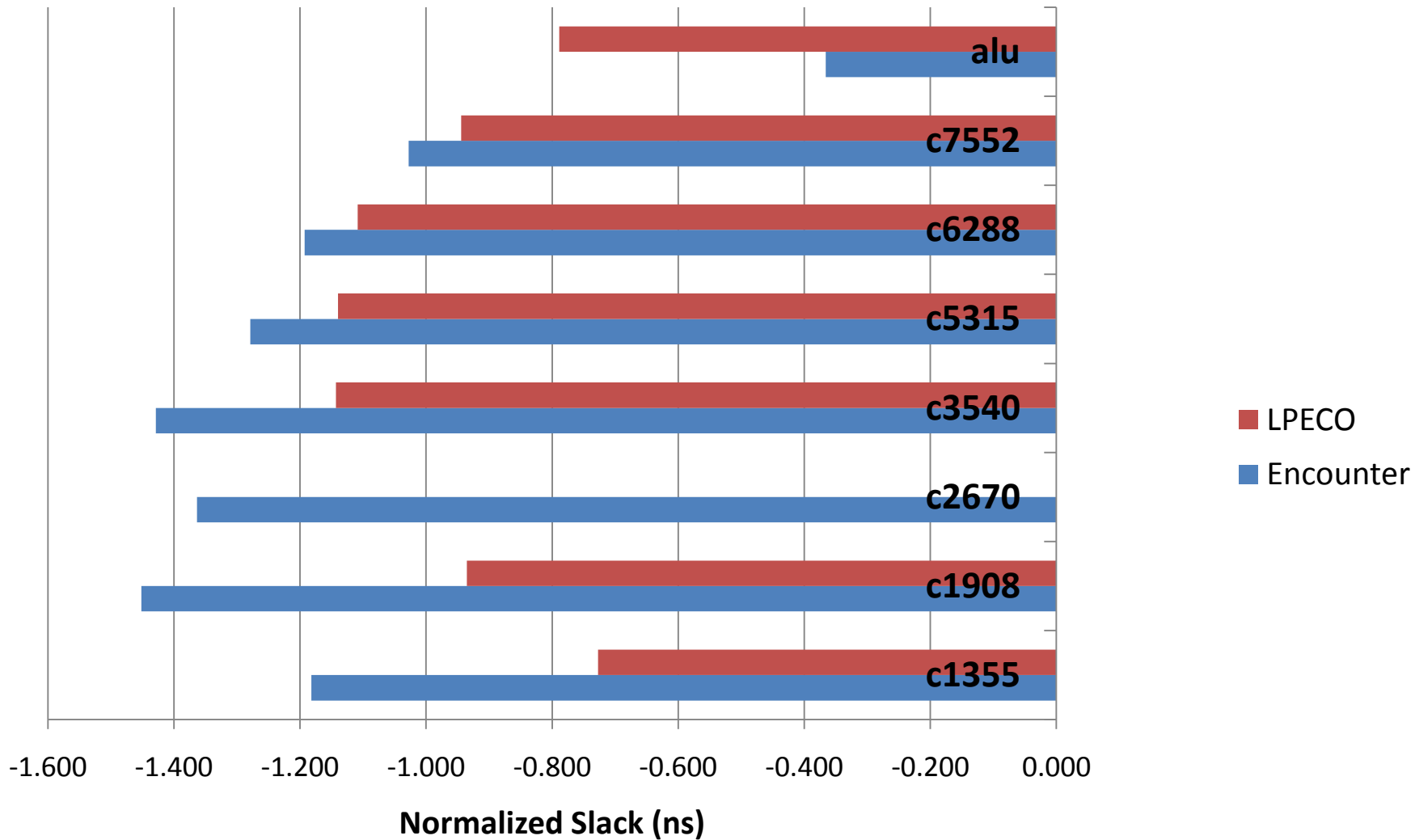
# Results: Timing Cost Comparison



# Results: Leakage Power



# Results: Slack (Infeasible Cases)



# Summary

- Quantified ECO Costs:
  - ECO Timing Cost
  - ECO Area Cost
- Performed incremental optimization to minimize ECO costs using LPECO
- Method performs well compared to commercial tool:
  - 22% to 88% reduction in ECO Area
  - 1% to 67% reduction in ECO Timing Cost
- Future goals:
  - Initial designs that incur small ECO penalties in the future
  - Large scale examples